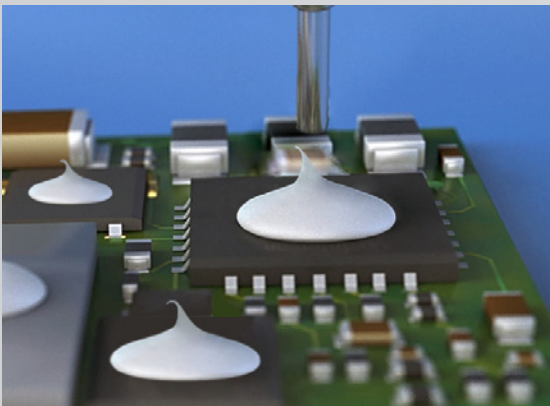




BERGQUIST LIQUI-FORM TLF 6000HG

THERMALLY CONDUCTIVE, ONE-PART, LIQUID FORMABLE GEL MATERIAL

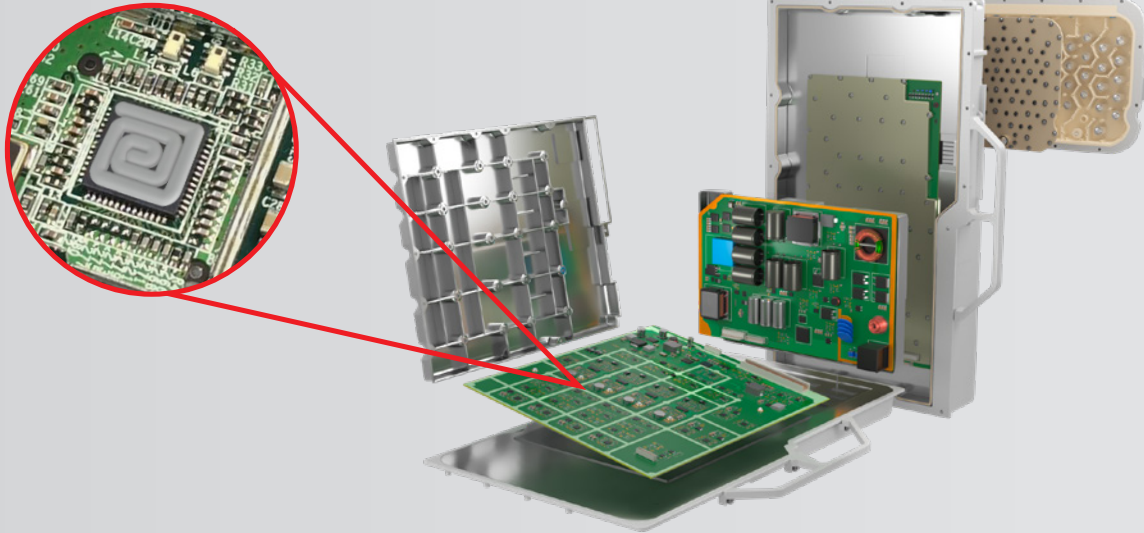
Addressing the requirements of demanding 5G telecom applications, Henkel's *BERGQUIST LIQUI-FORM TLF 6000HG* is a liquid form gel thermal interface material designed to meet the performance needs of next-generation 5G base station and remote antenna systems. The pre-cured, one-part gel can accommodate gaps as large as 3.0 mm, has a thermal conductivity of 6.0 W/m-K, and delivers highly reliable vertical gap stability for rugged in-field performance.



TYPICAL APPLICATIONS

- RRU/AAU/BBU in wireless in telecom wireless infrastructure
- Filling various gaps between heat-generating devices to heat sinks
- Devices requiring low assembly pressure
- High value assemblies with rework

Thermal Gel



KEY BENEFITS:

- High thermal conductivity (6.0 W/m-K) for optimum component cooling capability
- Superior vertical gap stability for gaps as large as 3.0 mm, no slipping during > 1,000 hrs. of gap stability testing
- Excellent thermal management consistency passed 1,000 hrs. of thermal cycling testing with no material cracking or degradation in thermal conductivity
- Automated dispensing capable, dispenses quickly to enable high-volume production
- UL-certified and RoHS-compliant

Technology	Silicone
Appearance	Grey Paste
Thermal Conductivity (W/m-K)	6.0
Dispense Rate, EFD 30 cc syringe, 90 psi*, grams/minute	17
Operating Temperature Range	-60 – 200°C
Volume Resistivity, 500 V DC, ASTM D257, (Ω-m)	4.37 × 10 ¹¹
UL Flammability Rating	UL 94 V-0

* 30 cc syringe, 90 psi (621 kPa), 0.100" orifice no attachment

**Across the Board,
Around the Globe.** 
henkel-adhesives.com/electronics

Henkel Corporation
14000 Jamboree Road
Irvine, CA 92606
United States
+1.888.943.6535

Henkel Europe
Nijverheidsstraat 7
B-2260, Westerlo
Belgium
+32.1457.5611

Henkel Asia
332 Meigui South Road
WaiGaoQiao FTZ
Shanghai 200131 China
+86.21.3898.4800